

**Features :**

- Isolated mounting base 2500V~
- Pressure contact technology with
Increased power cycling capability
- Space and weight savings

Typical Applications

- Welding

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{T(RMS)}	RMS on-state current	The two chips are assembled in reverse parallel and are continuous on current. T _{water} =30°C, 6L/min				970	A
		The two chips are assembled in reverse parallel ,usage rate 10%, twenty flowing on current continuously. T _{water} =30°C, 6L/min				1470	A
V _{DRM} /V _{RRM}	Repetitive peak off-state voltage Repetitive peak reverse voltage	tp=10ms	125			1600	V
I _{DRM} I _{RRM}	Repetitive peak current	at V _{DRM} at V _{RRM}	125			35	mA
I _{TSM}	Surge on-state current	10ms half sine wave	125			14.0	kA
I ² t	I ² t for fusing coordination	V _R =60%V _{RRM}					980
V _{TO}	Threshold voltage		125			0.90	V
r _T	On-state slope resistance						0.34
V _{TM}	Peak on-state voltage	I _{TM} =1710A	25			1.80	V
dv/dt	Critical rate of rise of off-state voltage	V _{DM} =67%V _{DRM}	125			800	V/μs
di/dt	Critical rate of rise of on-state current	Gate source 1.5A t _r ≤0.5μs Repetitive	125			100	A/μs
I _{GT}	Gate trigger current		25	30		200	mA
V _{GT}	Gate trigger voltage	V _A =12V, I _A =1A		0.8		3.0	V
I _H	Holding current			20		200	mA
V _{GD}	Non-trigger gate voltage	V _{DM} =67%V _{DRM}	125			0.2	V
I _{GD}	Non-trigger gate current	V _{DM} =67%V _{DRM}	125			10.0	mA
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled, per chip. DC				0.085	°C/W
R _{th(c-w)}	Thermal resistance case to water	Single side cooled, per chip. (6L/min)				0.051	°C/W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I _{iso} :1mA(MAX)		2500			V
F _m	Terminal connection torque(M10)			10.0		12.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		125	°C
T _{stg}	Stored temperature			-40		125	°C
T _{water}	Water temperature			-		30	°C
-	Water Pressure loss	Water flow=6L/min				36	kPa
W _t	Weight					1750	g
Outline	M14						

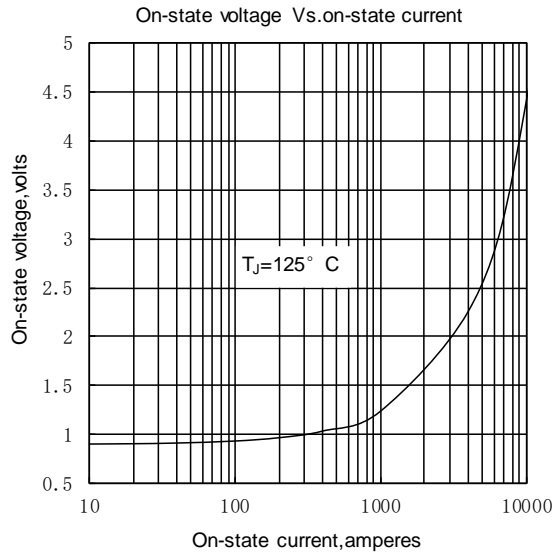


Fig.1

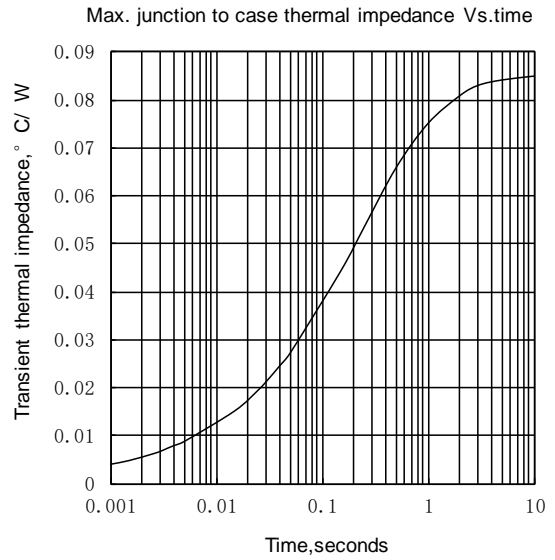


Fig.2

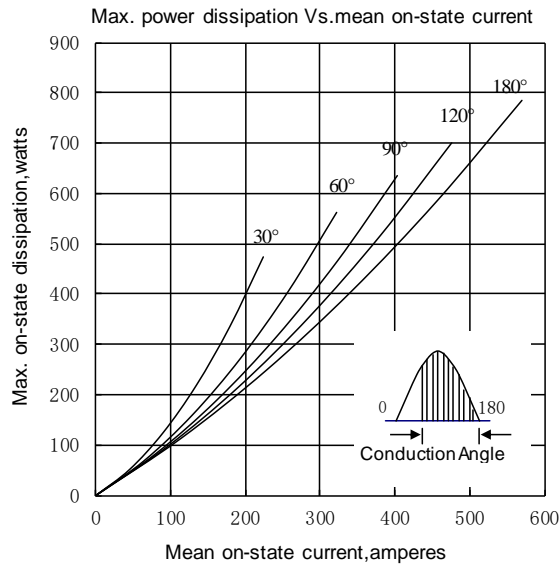


Fig.3

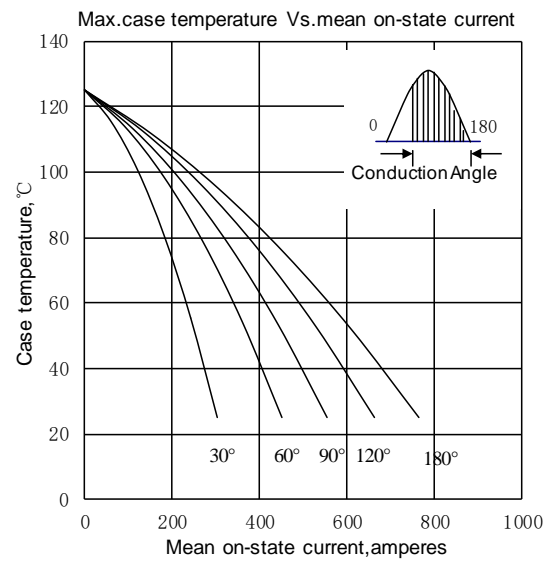


Fig.4

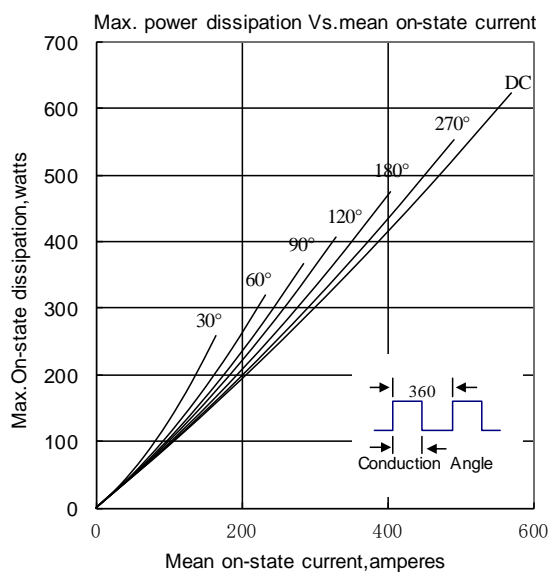


Fig.5

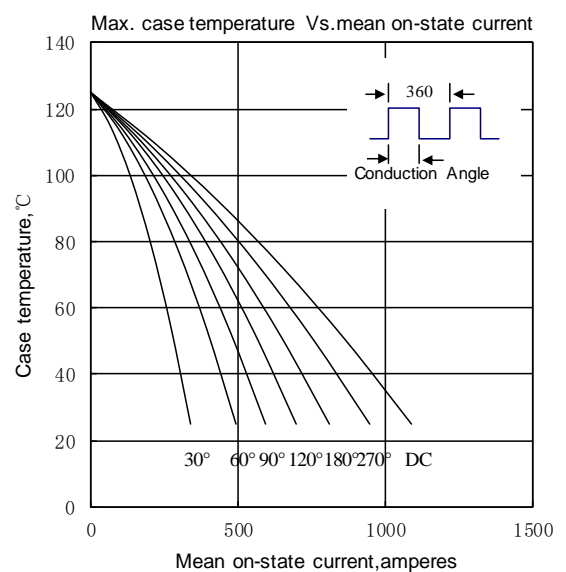


Fig.6

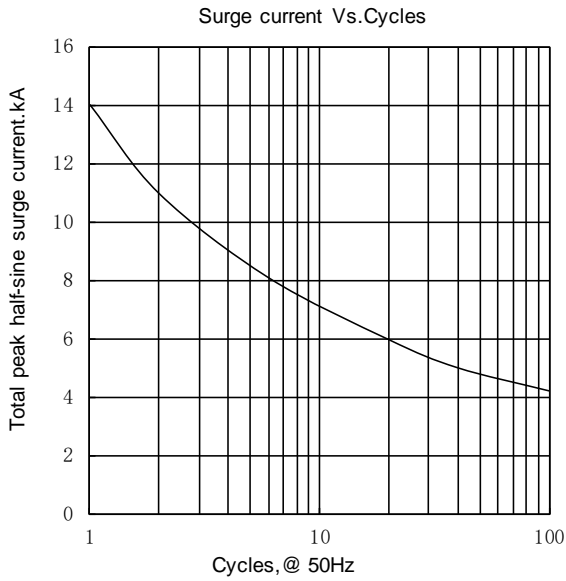


Fig.7

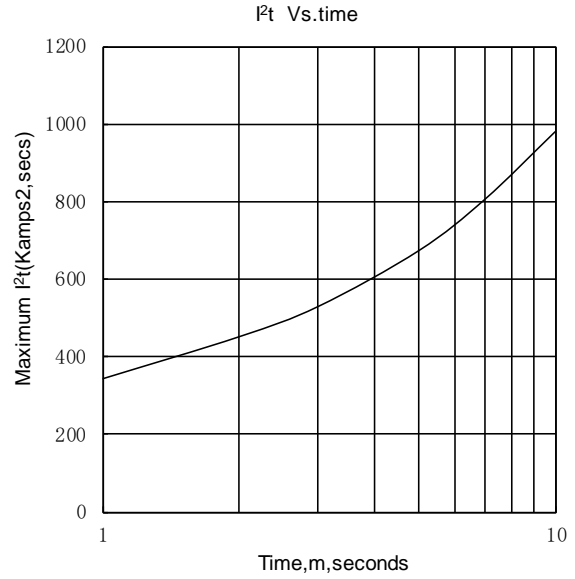


Fig.8

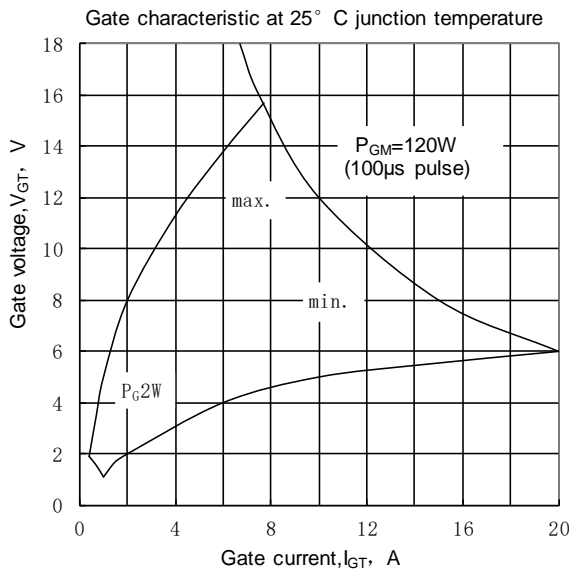


Fig.9

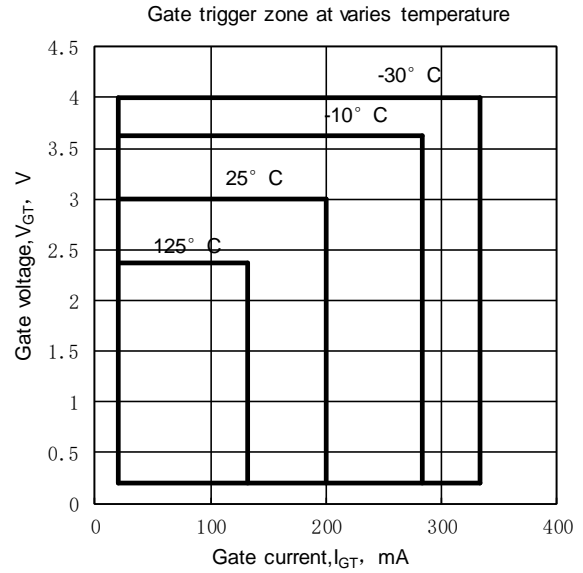


Fig.10

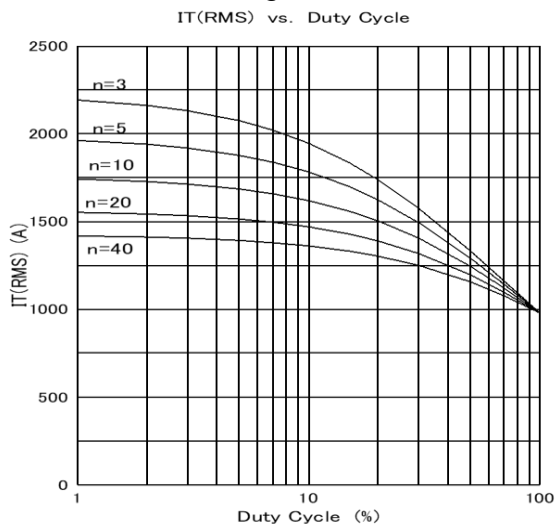


Fig.11

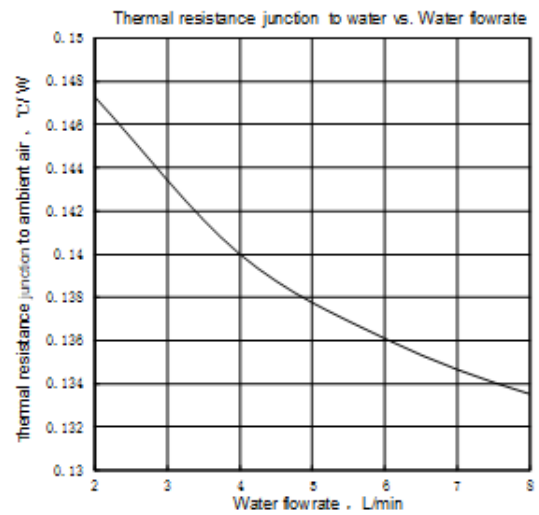


Fig.12

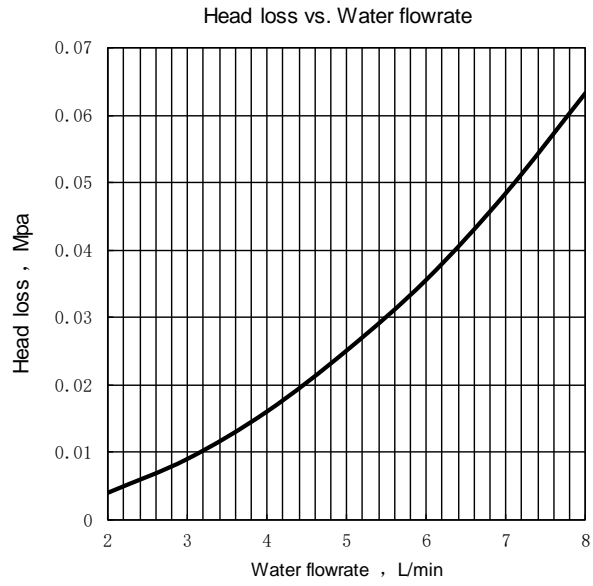
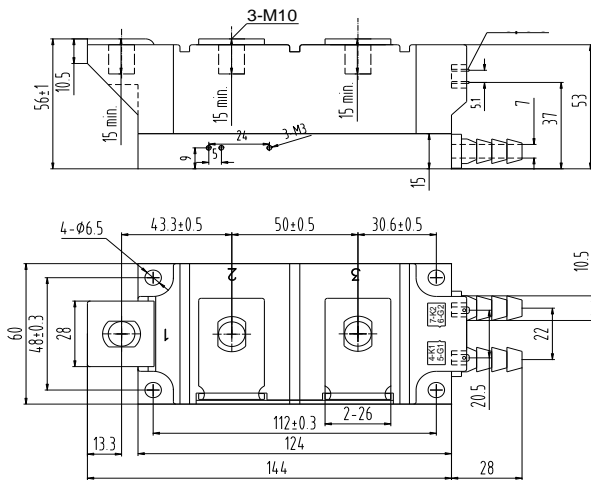


Fig.13



MD570T160W

